

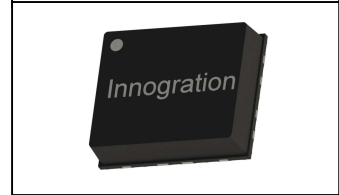


# 80W,28V Plastic RF LDMOS Transistor

**ITEH27080C9**

## Description

The ITEH27080C9 is an 80-watt, high performance, LDMOS transistor, designed for any general applications at frequencies from 2.5 to 2.7GHz, in 12\*10mm QFN plastic package, It can be soldered on PCB through high density grounding vias for pulse or back off linear application or soldered directly on heatsink.for CW application



- Typical 2.5-2.7GHz Class AB RF Performance (On Innogrations fixture with device soldered).

<b><math>V_{DS}= 28V, V_{GS}=2.65V(I_{dQ}=500mA),</math></b>				
<b><math>P_{out}=39.0dBm, WCDMA 1 Carrier</math></b>				
<b>Freq (MHz)</b>	<b>P3dB(W)</b>	<b>ACPR (dBc)</b>	<b>Gain(dB)</b>	<b>EFF (%)</b>
<b>2500</b>	<b>85.9</b>	<b>-42.91</b>	<b>15.8</b>	<b>16.1</b>
<b>2600</b>	<b>86.8</b>	<b>-40.30</b>	<b>15.9</b>	<b>16.4</b>
<b>2700</b>	<b>82.3</b>	<b>-41.75</b>	<b>15.8</b>	<b>17.2</b>

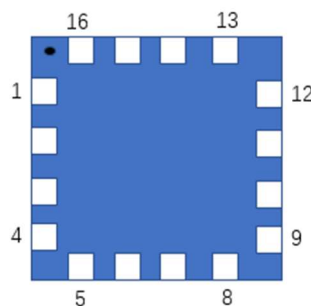
## Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

## Suitable Applications

- S band power amplifier
- All 4G/5G cellular application within 2.5 to 2.7GHz

## Pin Configuration and Description (Top view)



<b>Pin No.</b>	<b>Symbol</b>	<b>Description</b>
5-8	RF IN/Vgs	RF Input/Gate bias
13-16	RF OUT/Vds	RF Output/Drain bias
Others	NC	Can be left as either no use or grounding
Package Base	GND	DC/RF Ground. Proposed to be soldered to heatsink plane directly for the best CW thermal and RF performance. Soldered through vias or copper coin allowed for pulsed CW applications, but will result in excessive junction temperatures and different RF performance



**Table 1. Maximum Ratings**

Rating	Symbol	Value	Unit
Drain--Source Voltage	$V_{DS}$	+65	Vdc
Gate--Source Voltage	$V_{GS}$	-10 to +10	Vdc
Operating Voltage	$V_{DD}$	+28	Vdc
Storage Temperature Range	$T_{stg}$	-65 to +150	°C
Case Operating Temperature	$T_c$	+150	°C
Operating Junction Temperature	$T_j$	+225	°C

**Table 2. Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_c = 85^\circ\text{C}$ , DC test, <b>device soldered on heatsink directly</b>	$R_{\theta JC}$	0.9	°C/W

**Table 3. ESD Protection Characteristics**

Test Methodology	Class
Human Body Model (per JESD22--A114)	Class 2

**Table 4. Electrical Characteristics** ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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**DC Characteristics**

Drain-Source Voltage $V_{GS}=0, I_{DS}=100\mu\text{A}$	$V_{(BR)DSS}$		65	70	V
Zero Gate Voltage Drain Leakage Current ( $V_{DS} = 28\text{V}, V_{GS} = 0\text{V}$ )	$I_{DSS}$	---	---	1	$\mu\text{A}$
Gate--Source Leakage Current ( $V_{GS} = 11\text{V}, V_{DS} = 0\text{V}$ )	$I_{GSS}$	---	---	1	$\mu\text{A}$
Gate Threshold Voltage ( $V_{DS} = 28\text{V}, I_D = 600\mu\text{A}$ )	$V_{GS(th)}$	---	2	---	V
Gate Quiescent Voltage ( $V_{DD} = 28\text{V}, I_D = 600\text{mA}$ , Measured in Functional Test)	$V_{GS(Q)}$	---	2.6	---	V

**Load Mismatch (In Innogrations Test Fixture, 50 ohm system):**  $V_{DD} = 28\text{Vdc}, I_{DQ} = 600\text{mA}, f = 2700\text{MHz}$

VSWR 10:1 at 80W pulse CW Output Power	No Device Degradation
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## 2500-2700MHz application board

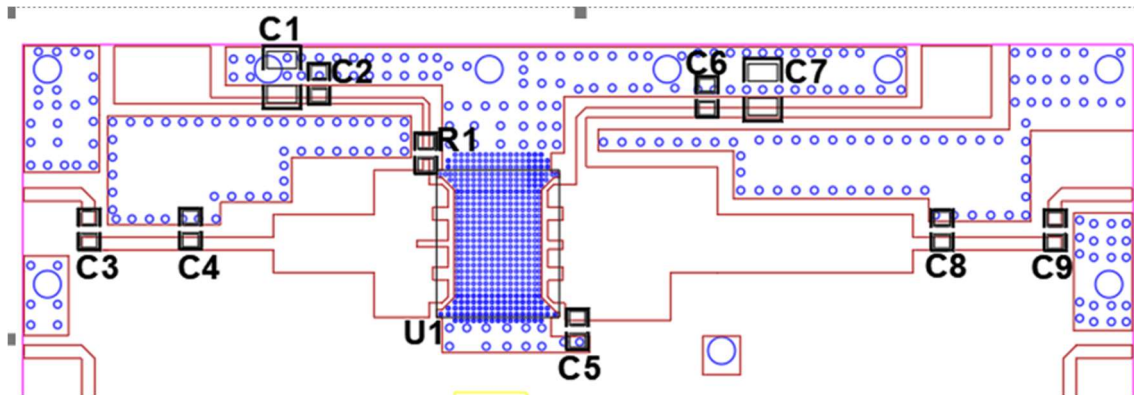


Figure 2. Test Circuit Component Layout, 20mils RO4350B

Table 5. Test Circuit Component Designations and Values

Component	Value	Description
PCB	Thickness,20mil	Rogers 4350
U1	ITEH27080C9	PA
C1、C7	10uF	TDK1206
C2、C3、C6、C9	10pF	ATC600S
C4	1.1pF	ATC600S
C5	1.6pF	ATC600S
C8	1.2pF	ATC600S
R1	10 Ω	TDK0805



### TYPICAL CHARACTERISTICS

Figure 3. Power Gain and Drain Efficiency as function of Power Output

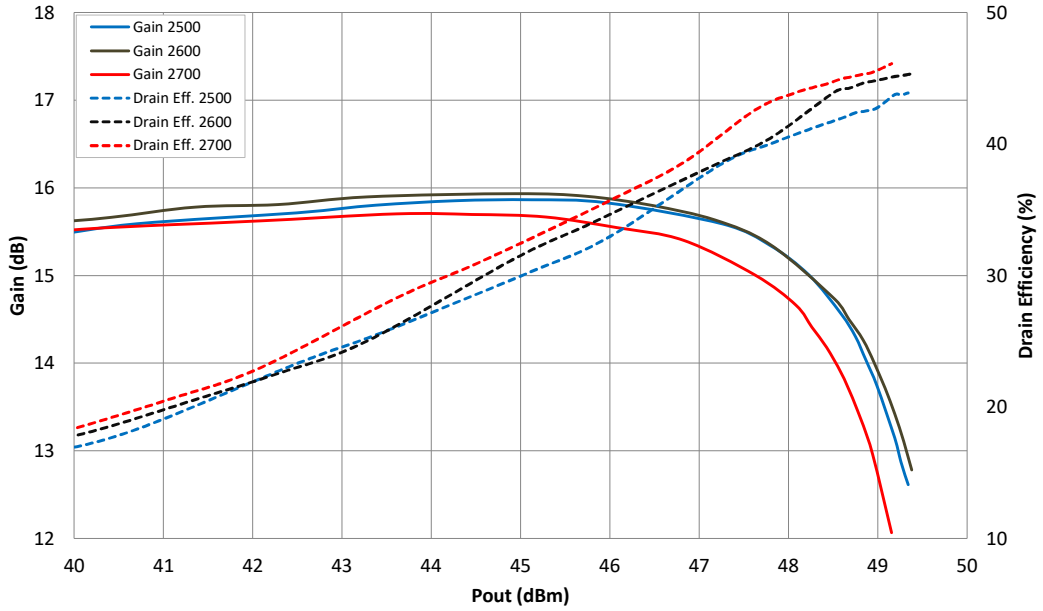
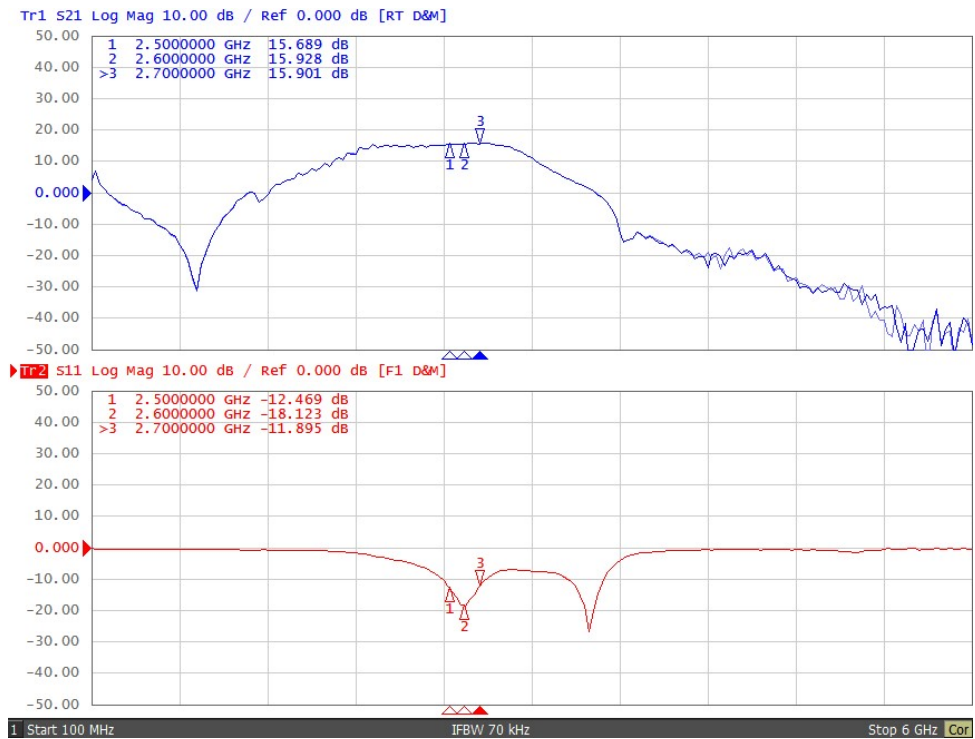
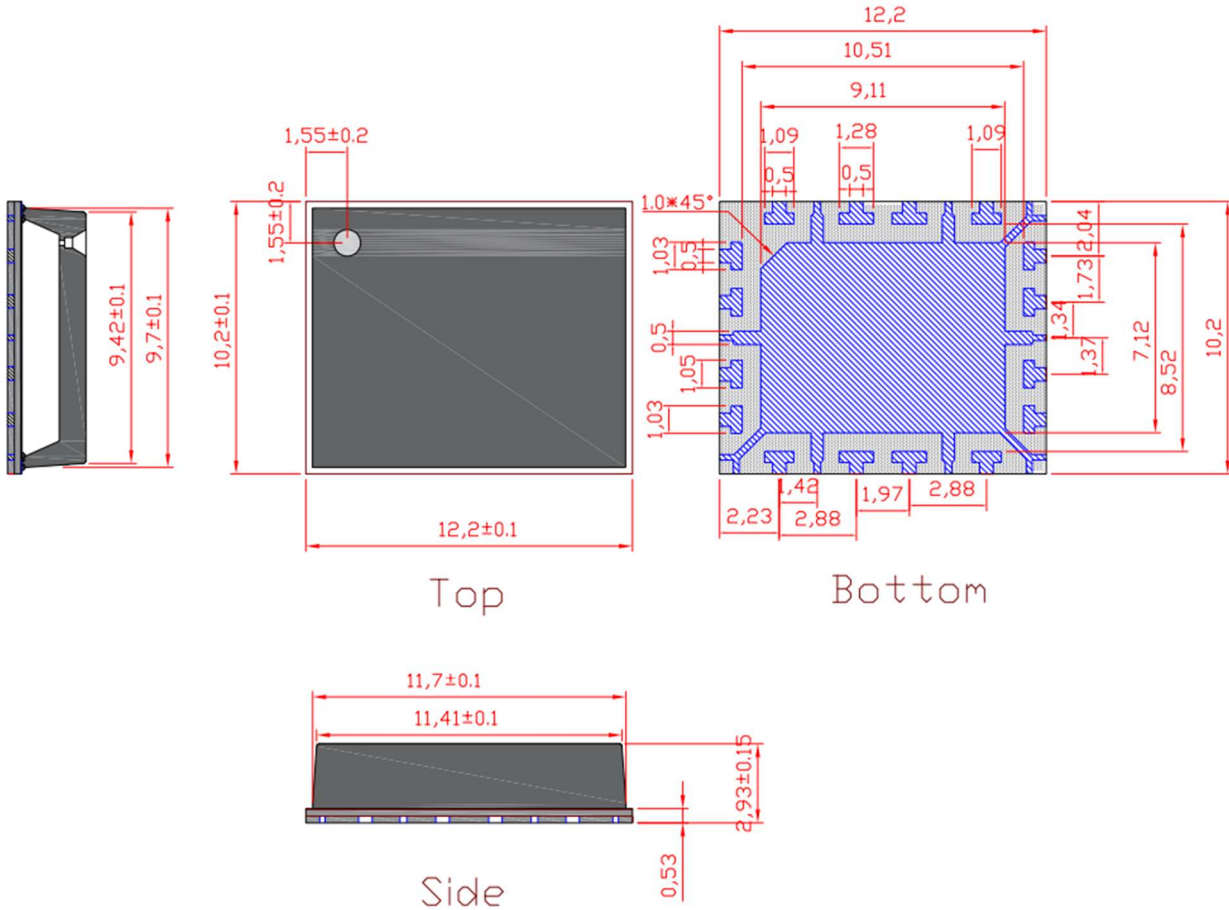


Figure 4. Network analyzer output S11/S21





### Package Dimensions



### Revision history

Table 7. Document revision history

Date	Revision	Datasheet Status
2023/12/11	Rev 1.0	Preliminary Datasheet

Application data based on HJ-23-24

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